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PSP-Based MOSVAR v1.0.0

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Abstract: The MOS varactor compact model is based in part on the PSP MOSFET model and is intended for analogue and RF-design. It includes dynamic inversion, finite poly doping, quantum mechanics, tunneling currents, and parasitics to model advanced MOS technologies. This manual contains a description of the PSP-based varactor model, including introduction, parameter sets, model equations, and parameter extraction procedure.

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Section 1

Introduction

The PSP-based varactor model is a compact MOS model intended for analog and radio-frequency circuit design. It includes dynamic inversion, finite poly doping, quantum mechanics, gate tunneling for different polarity combinations, and parasitics to model advanced MOS technologies.

1.1 Device Structure

Figure 1.1 shows a cross section of the standard MOS varactor offered in the current MOS technologies with its equivalent circuit model overlapped on it. **g**, **bi** and **b** are the external terminals while **gii**, **gi** and **ci** are the internal nodes. See Table 1.1 for the meaning of other symbols.

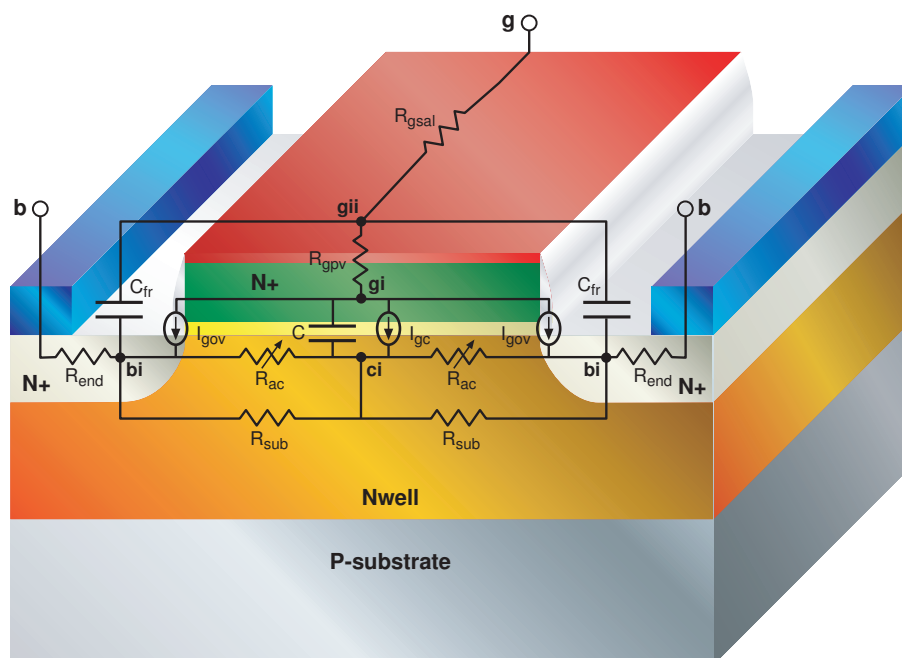


Figure 1.1: Cross section of MOS varactor with its equivalent circuit model.

Table 1.1: Components of varactor model

No.	Name	Description
1	C	Gate-channel capacitance
2	C _{fr}	Fringe and overlap capacitance
3	I _{gc}	Gate-channel current
4	I _{gov}	Gate-overlap current
5	R _{gsal}	Metal resistance
6	R _{gpv}	Poly gate resistance
7	R _{ac}	Accumulation resistance
8	R _{sub}	Substrate (in well region) resistance
9	R _{end}	End resistance

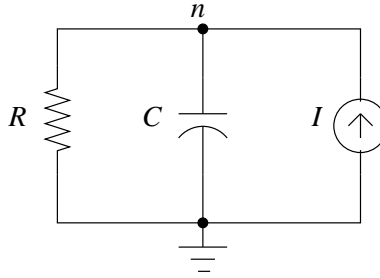


Figure 1.2: An RC circuit model used in the varactor code.

1.2 An RC Circuit Model for Inversion Charge

Figure 1.2 shows an RC circuit using in Section 4 for dynamic inversion charge [2, 3] with $R = 1\Omega$, $C = \mathbf{TAU}$ F, which is defined in Section 2, and a current source $I = q_{i0}$ A with q_{i0} the quasi-static inversion charge (only the values of \mathbf{TAU} and q_{i0} are used here). As can be seen, it performs the operation

$$q_i = q_{i0} - \mathbf{TAU} \cdot \frac{dq_i}{dt} \quad (1.1)$$

From the internal node n , the calculation results can be obtained. Note that the RC circuit is used only for computing convenience, it does not exist in the physical model.

1.3 Differences with PSP MOSFET Model

Although varactor model has inherited the surface potential algorithm from the PSP model [1], there are differences between them.

1. There is no position dependence of surface potential in varactor.
2. Dynamic formation of inversion region is included in the varactor model [2, 3].

3. Different (more elaborate) parasitics are included in the varactor model.
4. The varactor model has different combinations of gate and well polarities.
5. More elaborate polysilicon space charge region model are included in the varactor model (in PSP, there is no poly space charge effect in accumulation).
6. The varactor model is global, there is no local model.
7. The varactor model has simpler parameter clamping procedure.

Section 2

Constants and Parameters

In this section, the symbolic representation, value, and description of various physical constants and parameters used in the varactor model are listed. Throughout this document, varactor parameter names are all printed in boldface capitals. Parameters for temperature scaling start with ‘**ST**’, followed by the name of the parameter to which the temperature scaling applies.

2.1 Circuit Simulator Variables

External electrical variables

The definitions of the external electrical variables are shown in the following.

Symbol	Unit	Description
V_G^e	V	Potential applied to gate node
V_B^e	V	Potential applied to bulk node
I_G^e	A	DC current into gate node
I_B^e	A	DC current into bulk node
S_{fi}^e	A ² s	Spectral density of flicker noise current in the channel
S_{id}^e	A ² s	Spectral density of thermal noise current in the channel

Other circuit simulator variables

Next to the electrical variables described above, the quantities in the table below are also provided to the model by the circuit simulator.

Symbol	Unit	Description
T_A	°C	Ambient circuit temperature
f_{op}	Hz	Operation frequency

2.2 Model Constants

No.	Symbol	Unit	Value	Description
1	T_0	K	273.15	Offset between Celsius and Kelvin temperature scale
2	k_B	J/K	$1.3806505 \cdot 10^{-23}$	Boltzmann constant
3	\hbar	J s	$1.05457168 \cdot 10^{-34}$	Reduced Planck constant
4	q	C	$1.6021918 \cdot 10^{-19}$	Elementary unit charge
5	m_0	kg	$9.1093826 \cdot 10^{-31}$	Electron rest mass
6	ϵ_{ox}	F/m	$3.453 \cdot 10^{-11}$	Absolute permittivity of oxide
7	ϵ_{si}	F/m	$1.045 \cdot 10^{-10}$	Absolute permittivity of silicon
8	QM_N	$V m^{\frac{4}{3}} C^{-\frac{2}{3}}$	5.951993	Constant of quantum-mechanical behavior of electrons
9	QM_P	$V m^{\frac{4}{3}} C^{-\frac{2}{3}}$	7.448711	Constant of quantum-mechanical behavior of holes

2.3 Instance Parameters

No.	Name	Unit	Default	Min.	Max.	Description
1	L	m	10^{-6}	0	–	Design length of varactor
2	W	m	10^{-6}	0	–	Design width of varactor
3	m		1	0	–	Multiplicity factor
4	NGCON		1	1	2	Number of gate contacts
5	DTA	°C	0	–	–	Local temperature offset with respect to ambient circuit temperature

2.4 Special Model Parameters

No.	Name	Unit	Default	Min.	Max.	Description
1	Version		1	N/A	N/A	Model version
2	Revision		0.5	N/A	N/A	Model revision (subversion)
3	TMIN	°C	-100	-250	21	Minimum ambient temperature
4	TMAX	°C	500	21	1000	Maximum ambient temperature
5	VMAX	V	10000	0	–	Maximum voltage across node g and b

2.5 Model Parameters

No.	Name	Unit	Default	Min.	Max.	Description
1	LEVEL		1000	N/A	N/A	Model level
2	TR	°C	21	-250	1000	Nominal (reference) temperature
3	LMIN	m	10^{-8}	0	—	Minimum allowed drawn length
4	LMAX	m	$9.9 \cdot 10^{-8}$	0	—	Maximum allowed drawn length
5	WMIN	m	10^{-8}	0	—	Minimum allowed drawn width
6	WMAX	m	$9.9 \cdot 10^{-8}$	0	—	Maximum allowed drawn width
7	TOXO	m	$2 \cdot 10^{-9}$	$5 \cdot 10^{-10}$	$2 \cdot 10^{-8}$	Oxide thickness
8	VFBO	V	0.0	—	—	Flat-band voltage ¹
9	NSUBO	m^{-3}	$3 \cdot 10^{23}$	10^{22}	10^{25}	Substrate doping level
10	MNSUBO		1	1	10	Maximum change in absolute doping, limited to 1 order of magnitude up
11	DNSUBO		0	0	100	Doping profile slope parameter
12	VNSUBO		0	-5	5	Doping profile corner voltage parameter
13	NSLPO		0.1	0.1	1	Doping profile smoothing parameter
14	DLQ	m	0	—	—	Length delta for capacitor size
15	DWQ	m	0	—	—	Width delta for capacitor size
16	DWR	m	0	—	—	Width delta for substrate resistance calculation
17	CFRL	F/m	0	0	—	Fringing capacitance in length direction
18	CFRW	F/m	0	0	—	Fringing capacitance in width direction
19	RSHG	Ω/sq	1	0	—	Gate sheet resistance
20	RPV	$\Omega \cdot m^2$	0	0	—	Vertical resistance down through gate
21	REND	$\Omega \cdot m$	10^{-4}	0	—	End resistance (extrinsic well res. plus vertical contact res. to well) per width
22	RSHS	Ω/sq	1000	0	10000	Substrate sheet resistance

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¹In PSP, VFBO corresponds to NMOS and is negative of the actual value for PMOS. For varactor, one specifies the actual value.

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No.	Name	Unit	Default	Min.	Max.	Description
23	UAC	m ² /V/s	5 · 10 ⁻²	0	–	Accumulation layer zero-bias mobility
24	UACRED	V ⁻¹	0	0	–	accumulation layer mobility degradation factor
25	STVFB	V/K	0	–	–	Temperature dependence of V _{fb}
26	STRSHG		0	–	–	Temperature dependence of R _{shg}
27	STRPV		0	–	–	Temperature dependence of R _{pv}
28	STREND		0	–	–	Temperature dependence of R _{end}
29	STRSHS		0	–	–	Temperature dependence of R _{shs}
30	STUAC		0	–	–	Temperature dependence of U _{ac}
31	FETA		1.0	0	–	Effective field parameter
Switch or switch-like parameters						
32	SWRES		1	0	1	Switch to control series resistance: 0→ exclude; 1→ include
33	TYPE		-1	-1	1	Substrate doping type: -1→ n-type; +1→ p-type
34	TYPEP		-1	-1	1	Polysilicon doping type: -1→ n-type; +1→ p-type
35	TAU	s	0.1	0	10	Time constant for inversion charge recombination/generation
36	NPO	m ⁻³	10 ²⁷	10 ²⁴	10 ²⁷	Polysilicon doping level
37	QMC		1	0	–	Quantum mechanical correction factor
38	SWGATE		0	0	1	Flag for gate current: 0→turn off; 1→turn on
Additional model parameters for gate tunneling currents						
39	CHIBO	V	3.1	1.0	–	Tunneling barrier height for electrons
40	CHIBPO	V	4.5	1.0	–	Tunneling barrier height for holes
41	LOV	m	0	0	–	Overlap length
42	NOVO	m ⁻³	5 · 10 ²⁵	10 ²²	10 ²⁶	Effective doping level of overlap regions

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No.	Name	Unit	Default	Min.	Max.	Description
43	IGINVLW	A	0	0	–	ECB gate channel current pre-factor for 1 μm^2 channel area
44	IGOVW	A	0	0	–	ECB gate overlap current pre-factor for 1 μm wide gate overlap region
45	GCOO		0	–10	10	ECB gate tunneling energy adjustment
46	GC2O		0.375	0	10	ECB gate current slope factor
47	GC3O		0.063	–10	10	ECB gate current curvature factor
48	IGCHVLW	A	0	0	–	HVB gate channel current pre-factor for 1 μm^2 channel area
49	IGOVHVV	A	0	0	–	HVB gate overlap current pre-factor for 1 μm wide gate overlap region
50	GCOHVO		0	–10	10	HVB gate tunneling energy adjustment
51	GC2HVO		0.375	0	10	HVB gate current slope factor
52	GC3HVO		0.063	–10	10	HVB gate current curvature factor
53	IGCEVLW	A	0	0	–	EVB gate channel current pre-factor for 1 μm^2 channel area
54	IGOVEVW	A	0	0	–	EVB gate overlap current pre-factor for 1 μm wide gate overlap region
55	GCOEVO		0	–10	10	EVB gate tunneling energy adjustment
56	GC2EVO		0.375	0	10	EVB gate current slope factor
57	GC3EVO		0.063	–10	10	EVB gate current curvature factor

Section 3

Parameter Initializing

In this section, internal parameters, such as effective channel length and width, body factors, are initialized or calculated to prepare for the calculation of the surface potential, charges, and currents in the next section.

3.1 Capacitance of Oxide and Body Factors

$$C_{\text{ox}} = \epsilon_{\text{ox}} / \text{TOXO} \quad (3.1)$$

$$\gamma_s = \sqrt{2 \cdot q \cdot \epsilon_{\text{si}} \cdot \text{NSUBO}} / C_{\text{ox}} \quad (3.2)$$

$$\gamma_p = \sqrt{2 \cdot q \cdot \epsilon_{\text{si}} \cdot \text{NPO}} / C_{\text{ox}} \quad (3.3)$$

$$\gamma_{\text{ov},s} = \sqrt{2 \cdot q \cdot \epsilon_{\text{si}} \cdot \text{NOVO}} / C_{\text{ox}} \quad (3.4)$$

$$\text{If } \mathbf{QMC} > 0 \quad q_q = \begin{cases} 0.4 \cdot \mathbf{QMN} \cdot \mathbf{QMC} \cdot (C_{\text{ox}})^{2/3}, & \text{if } \mathbf{TYPE} > 0 \\ 0.4 \cdot \mathbf{QMP} \cdot \mathbf{QMC} \cdot (C_{\text{ox}})^{2/3}, & \text{otherwise} \end{cases} \quad (3.5)$$

$$\text{else } q_q = 0 \quad (3.6)$$

$$\eta_\mu = \begin{cases} 0.5 \cdot \mathbf{FETA}, & \text{if } \mathbf{TYPE} > 0 \\ \frac{1}{3} \cdot \mathbf{FETA}, & \text{otherwise} \end{cases} \quad (3.7)$$

$$\text{norm}_{\text{tox}} = \text{TOXO} / 10^{-9}; \quad (3.8)$$

3.2 Initializing Parameters

Temperature-Related Parameters

$$\text{TR1} = \begin{cases} \mathbf{TR}, & \text{if } \mathbf{TR} \geq -273 \\ -273, & \text{if } \mathbf{TR} < -273 \end{cases} \quad (3.9)$$

$$T_{KR} = 273.15 + TR1 \quad (3.10)$$

$$T_{KD} = T_A + DTA \quad (3.11)$$

$$\Delta T = T_{KD} - T_{KR} \quad (3.12)$$

$$\phi_T = k_B \cdot T_{KD} / q \quad (3.13)$$

$$q_{lim2} = 100 \cdot \phi_T^2 \quad (3.14)$$

$$V_{fb, T} = VFBO + \Delta T \cdot STVFB \quad (3.15)$$

$$R_{shg, T} = RSHG \cdot \left(\frac{T_{KR}}{T_{KD}} \right)^{STRSHG} \quad (3.16)$$

$$R_{pv, T} = RPV \cdot \left(\frac{T_{KR}}{T_{KD}} \right)^{STRPV} \quad (3.17)$$

$$R_{end, T} = REND \cdot \left(\frac{T_{KR}}{T_{KD}} \right)^{STREND} \quad (3.18)$$

$$R_{shs, T} = RSHS \cdot \left(\frac{T_{KR}}{T_{KD}} \right)^{STRSHS} \quad (3.19)$$

$$U_{ac, T} = UAC \cdot \left(\frac{T_{KD}}{T_{KR}} \right)^{STUAC} \quad (3.20)$$

General Parameters

$$nt0 = 4 \cdot 'KBOL \cdot T_{KD} \quad (3.21)$$

$$L_{eff} = L + DLQ \quad (3.22)$$

$$W_{eff} = W + DWQ \quad (3.23)$$

$$M_{eff} = M_SEG \cdot 'MFACTOR_USE \quad (3.24)$$

$$INV_{Meff} = 1.0 / M_{eff} \quad (3.25)$$

$$E_g = 1.179 - T_{KD} \cdot (9.025 \cdot 10^{-5} + 3.05 \cdot 10^{-7} \cdot T_{KD}) \quad (3.26)$$

$$r_T = (1.045 + 4.5 \cdot 10^{-4} \cdot T_{KD}) \cdot (0.523 + 1.4 \cdot 10^{-3} \cdot T_{KD} - 1.48 \cdot 10^{-6} \cdot T_{KD}^2) \cdot \frac{T_{KD}^2}{90000} \quad (3.27)$$

$$INV_{ni} = 4 \cdot 10^{-26} \cdot r_T^{-0.75} \quad (3.28)$$

$$\phi_b = E_g + 2 \cdot \phi_T \cdot \ln(NSUBO \cdot INV_{ni}) \quad (3.29)$$

$$k_{se1} = 230.26 \quad (3.30)$$

$$k_{se2} = 460.52 \quad (3.31)$$

Parameters Related to Polysilicon and Overlap Regions

$$G_p = \gamma_p / \sqrt{\phi_T} \quad (3.32)$$

$$\xi_p = 1 + G_p / \sqrt{2} \quad (3.33)$$

$$x_{mrgp} = 10^{-5} \cdot \xi_p \quad (3.34)$$

$$\phi_p = E_g + 2 \cdot \phi_T \cdot \ln(\mathbf{NPO} \cdot \mathbf{INV}_{ni}) \quad (3.35)$$

$$x_{np} = \phi_p / \phi_T \quad (3.36)$$

$$\Delta_{np} = \begin{cases} \exp(-x_{np}), & \text{if } x_{np} < k_{se2} \\ \frac{10^{-200}}{\mathbf{P3}(x_{np} - k_{se2})}, & \text{otherwise} \end{cases} \quad (3.37)$$

$$G_{ov,s} = \gamma_{ov,s} / \sqrt{\phi_T} \quad (3.38)$$

$$\xi_{ov,s} = 1 + G_{ov,s} / \sqrt{2} \quad (3.39)$$

$$x_{mrgov,s} = 10^{-5} \cdot \xi_{ov,s} \quad (3.40)$$

$$\phi_{b,ov} = E_g + 6 \cdot \phi_T \quad (3.41)$$

$$x_1 = 1.25 \quad (3.42)$$

$$x_{g1,ov} = x_1 + G_{ov,s} \cdot \sqrt{\exp(-x_1) + x_1 - 1} \quad (3.43)$$

Fringing Capacitance

$$C_{fr} = 2 \cdot (\mathbf{CFRW} \cdot W + \mathbf{CFRL} \cdot L) \quad (3.44)$$

Resistances

$$\begin{array}{l}
 \text{If SWRES = true} \\
 \left\{ \begin{array}{l}
 R_{\text{gsal}} = \frac{R_{\text{shg},T} \cdot W}{L \cdot [3 + 9 \cdot (\text{NGCON} - 1)]} \\
 R_{\text{gpv}} = \frac{R_{\text{pv},T}}{W \cdot L} \\
 R_{\text{end}} = \frac{R_{\text{end},T}}{2 \cdot (W + \text{DWR})} \\
 R_{\text{sub}} = \frac{R_{\text{shs},T} \cdot L}{12 \cdot (W + \text{DWR})} \\
 R_{\text{gsal}} = \text{'CLIP_BOTH}(R_{\text{gsal}}, 1.0e - 03, 1e01) \\
 R_{\text{gpv}} = \text{'CLIP_BOTH}(R_{\text{gpv}}, 1.0e - 03, 1e02) \\
 R_{\text{end}} = \text{'CLIP_BOTH}(R_{\text{end}}, 1.0e - 03, 1e01) \\
 R_{\text{sub}} = \text{'CLIP_BOTH}(R_{\text{sub}}, 1.0e - 03, 1e03) \\
 U_{\text{ac},T} = \text{'CLIP_BOTH}(U_{\text{ac},T}, 1.0e - 03, 2e01) \\
 G_{\text{gsal}} = 1/R_{\text{gsal}} \\
 G_{\text{gpv}} = 1/R_{\text{gpv}} \\
 G_{\text{end}} = 1/R_{\text{end}} \\
 G_{\text{sub}} = 1/R_{\text{sub}} \\
 G_{\text{ac0}} = 12 \cdot U_{\text{ac},T} \cdot W/L
 \end{array} \right. \quad (3.45)
 \end{array}$$

$$\begin{array}{l}
 \text{If SWRES = false} \\
 \left\{ \begin{array}{l}
 G_{\text{gsal}} = 0.0 \\
 G_{\text{gpv}} = 0.0 \\
 G_{\text{end}} = 0.0 \\
 G_{\text{sub}} = 0.0 \\
 G_{\text{ac0}} = 0.0
 \end{array} \right. \quad (3.46)
 \end{array}$$

Gate Tunneling Parameters

$$\begin{aligned}
 & \text{If } \mathbf{SWIGATE} = \text{true} \left\{ \begin{aligned}
 & I_{\text{ginv}} = \mathbf{IGINVLW} \cdot W_{\text{eff}} \cdot L_{\text{eff}} \cdot 10^{12} \cdot \left(\frac{T_{\text{KD}}}{T_{\text{KR}}} \right)^{\text{STIG}} \\
 & I_{\text{gov}} = 2 \cdot \mathbf{IGOVW} \cdot \mathbf{LOV} \cdot W_{\text{eff}} \cdot 10^{12} \cdot \left(\frac{T_{\text{KD}}}{T_{\text{KR}}} \right)^{\text{STIG}} \\
 & I_{\text{gcHVB}} = \mathbf{IGCHVLW} \cdot W_{\text{eff}} \cdot L_{\text{eff}} \cdot 10^{12} \cdot \left(\frac{T_{\text{KD}}}{T_{\text{KR}}} \right)^{\text{STIG}} \\
 & I_{\text{govHVB}} = 2 \cdot \mathbf{IGOVHVW} \cdot \mathbf{LOV} \cdot W_{\text{eff}} \cdot 10^{12} \cdot \left(\frac{T_{\text{KD}}}{T_{\text{KR}}} \right)^{\text{STIG}} \\
 & \mathbf{INV}_{\text{CHIB}} = 1/\mathbf{CHIBO} \\
 & \mathbf{INV}_{\text{CHIB, HVB}} = 1/\mathbf{CHIBPO} \\
 & B_{\text{CH}} = (4/3) \cdot \mathbf{TOXO} \cdot \sqrt{2 \cdot q \cdot m_0 \cdot \mathbf{CHIBO}} / \hbar \\
 & B_{\text{OV}} = B_{\text{CH}} \\
 & B_{\text{CH, HVB}} = (4/3) \cdot \mathbf{TOXO} \cdot \sqrt{2 \cdot q \cdot m_0 \cdot \mathbf{CHIBPO}} / \hbar \\
 & B_{\text{OV, HVB}} = B_{\text{CH, HVB}} \\
 & \text{If } \mathbf{GC30} < 0, Q_{\text{CQ}} = -0.495 \cdot \mathbf{GC20}/\mathbf{GC30}, \\
 & \text{else } Q_{\text{CQ}} = 0.0, \text{ endif} \\
 & \alpha_{\text{b, s}} = 0.5 \cdot (E_{\text{g}} + \mathbf{TYPE} \cdot \phi_{\text{b}}) \\
 & \alpha_{\text{b, ov}} = 0.5 \cdot (E_{\text{g}} + \mathbf{TYPE} \cdot \phi_{\text{b, ov}}) \\
 & D_{\text{ch}} = \mathbf{GCOO} \cdot \phi_{\text{T}} \\
 & D_{\text{ch, HVB}} = \mathbf{GCOO} \cdot \phi_{\text{T}}
 \end{aligned} \right. \tag{3.47}
 \end{aligned}$$

$$\begin{aligned}
 & \text{If } \mathbf{SWIGATE} = \text{false} \left\{ \begin{aligned}
 & I_{\text{ginv}} = 0 \\
 & I_{\text{gov}} = 0 \\
 & I_{\text{gcHVB}} = 0 \\
 & I_{\text{govHVB}} = 0 \\
 & \mathbf{INV}_{\text{CHIB}} = 0.1 \\
 & \mathbf{INV}_{\text{CHIB, HVB}} = 0.1 \\
 & B_{\text{CH}} = 0 \\
 & B_{\text{OV}} = 0 \\
 & B_{\text{CH, HVB}} = 0 \\
 & B_{\text{OV, HVB}} = 0 \\
 & Q_{\text{CQ}} = 0 \\
 & \alpha_{\text{b, s}} = 0 \\
 & \alpha_{\text{b, ov}} = 0 \\
 & D_{\text{ch}} = 0 \\
 & D_{\text{ch, HVB}} = 0
 \end{aligned} \right. \tag{3.48}
 \end{aligned}$$

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Section 4

Model Equations

4.1 Static Evaluations

$$N_{b, \text{lim}} = \text{NSUBO} \cdot \text{MNSUBO} \quad (4.1)$$

$$N_{b1} = \text{NSUBO} \cdot [1 + \text{DNSUBO} \cdot \text{MAXA}(\text{TYPE} \cdot (V_C - \text{VNSUBO}), 0, \text{NSLPO})], \quad (4.2)$$

where V_C is the voltage cross the capacitor C.

$$N_{b, v} = \text{NSUBO} \cdot \text{MINA}(N_{b1}/\text{NSUBO}, \text{MNSUBO}, 10^{-6}) \quad (4.3)$$

$$\text{norm}_{\text{nsb}} = N_{b, v}/10^{23} \quad (4.4)$$

$$\phi_{b1} = E_g + 2 \cdot \phi_T \cdot \ln(N_{b, v} \cdot \text{INV}_{\text{ni}}) \quad (4.5)$$

$$\gamma_{s1} = \sqrt{2 \cdot q \cdot \epsilon_{\text{si}} \cdot N_{b, v}} / C_{\text{ox}} \quad (4.6)$$

$$\text{If } \text{QMC} > 0 \left\{ \begin{array}{l} q_{b0} = \sqrt{\gamma_s^2 \cdot \phi_b} \\ d_{\phi_{\text{bq}}} = 0.75 \cdot q_q \cdot (q_{b0})^{2/3} \\ \phi_b = \phi_{b1} + d_{\phi_{\text{bq}}} \\ \gamma_s = \gamma_{s1} \cdot \left(1 + \frac{4}{3} \frac{d_{\phi_{\text{bq}}}}{q_{b0}}\right) \end{array} \right. \quad (4.7)$$

$$G_s = \gamma_s / \sqrt{\phi_T} \quad (4.8)$$

$$\xi_s = 1 + G_s / \sqrt{2} \quad (4.9)$$

$$x_{\text{mrgs}} = 10^{-5} \cdot \xi_s \quad (4.10)$$

$$x_{\text{ns}} = \phi_b / \phi_T \quad (4.11)$$

$$\Delta_{\text{ns}} = \begin{cases} \exp(-x_{\text{ns}}), & \text{if } x_{\text{ns}} < k_{\text{se}2} \\ \frac{10^{-200}}{\text{P3}(x_{\text{ns}} - k_{\text{se}2})}, & \text{otherwise} \end{cases} \quad (4.12)$$

$$x_{\text{g}1} = x_1 + G_s \cdot \sqrt{\exp(-x_1) + x_1 - 1} \quad (4.13)$$

$$x_{\text{g}1,\text{ov}} = x_1 + G_{\text{ov},s} \cdot \sqrt{\exp(-x_1) + x_1 - 1} \quad (4.14)$$

4.2 Calculation of the Surface Potential at the Channel Side

A macro Φ_s is defined to calculate the surface potential at the channel side with output x_s and inputs: x_g , x_{ns} , Δ_{ns} , G , G^2 , G^{-2} , ξ , ξ^{-1} , x_{mrg} . The definitions of the auxiliary functions MINA, MAXA, σ_1 , σ_2 , and others can be found in Appendix A.

$$\text{if } x_g < -x_{\text{mrg}} \left\{ \begin{array}{l} y_g = -x_g \\ z = 1.25 \cdot y_g / \xi \\ \eta = [z + 10 - \sqrt{(z - 6)^2 + 64}] / 2 \\ a = (y_g - \eta)^2 + G^2 \cdot (\eta + 1) \\ c = 2 \cdot (y_g - \eta) - G^2 \\ \tau = -\eta + \ln(a / G^2) \\ y_0 = \sigma_1(a, c, \tau, \eta) \\ \Delta_0 = \text{expl}_{\text{high}}(y_0) \\ p = 2 \cdot (y_g - y_0) + G^2 \cdot [\Delta_0 - 1 + \Delta_{\text{ns}} \cdot (1 - 1/\Delta_0)] \\ q = (y_g - y_0)^2 + G^2 \cdot [y_0 - \Delta_0 + 1 + \Delta_{\text{ns}} \cdot (1 - 1/\Delta_0 - 2 \cdot y_0)] \\ x_s = -y_0 - \frac{2 \cdot q}{p + \sqrt{p^2 - 2 \cdot q \cdot [2 - G^2 \cdot (\Delta_0 + \Delta_{\text{ns}}/\Delta_0)]}} \end{array} \right. \quad (4.15)$$

$$\text{if } |x_g| \leq x_{\text{mrg}} \left\{ x_s = \frac{x_g}{\xi} \cdot \left[1 + G \cdot x_g \cdot \frac{1 - \Delta_{\text{ns}}}{\xi^2 \cdot 6 \cdot \sqrt{2}} \right] \right. \quad (4.16)$$

$$\begin{aligned}
& \text{if } x_g > x_{\text{mrg}} \left\{ \begin{aligned}
& \hat{x}_{g1} = x_1 + G \cdot \sqrt{\exp(-x_1) + x_1 - 1} \\
& \bar{x} = \frac{x_g}{\xi} \cdot [1 + x_g \cdot (\xi \cdot x_1 - \hat{x}_{g1}) / \hat{x}_{g1}^2] \\
& x_0 = x_g + G^2/2 - G \cdot \sqrt{x_g + G^2/4 - 1 + \text{expl}_{\text{low}}(-\bar{x})} \\
& b_x = x_{\text{ns}} + 3 \\
& \eta = \text{MINA}(x_0, b_x, 5) - (b_x - \sqrt{b_x^2 + 5}) / 2 \\
& a = (x_g - \eta)^2 - G^2 \cdot [\exp(-\eta) + \eta - 1 - \Delta_{\text{ns}} \cdot (\eta + 1)] \\
& b = 1 - G^2/2 \cdot \exp(-\eta) \\
& c = 2 \cdot (x_g - \eta) + G^2 \cdot [1 - \exp(-\eta) - \Delta_{\text{ns}}] \\
& \tau = x_{\text{ns}} - \eta + \ln(a/G^2) \\
& y_0 = \sigma_2(a, b, c, \tau, \eta) \\
& \Delta_0 = \begin{cases} \exp(y_0), & \text{if } y_0 < k_{\text{se1}} \\ \exp(y_0 - x_{\text{ns}}), & \text{if } y_0 > x_{\text{ns}} - k_{\text{se1}} \\ \frac{10^{-100}}{\text{P3}(x_{\text{ns}} - y_0 - k_{\text{se1}})}, & \text{otherwise} \end{cases} \\
& p = 2 \cdot (x_g - y_0) + G^2 \cdot [1 - 1/\Delta_0 + \Delta_{\text{ns}} \cdot (\Delta_0 - 1)] \\
& q = (x_g - y_0)^2 - G^2 \cdot [y_0 + 1/\Delta_0 - 1 + \Delta_{\text{ns}} \cdot (\Delta_0 - y_0 - 1)] \\
& x_s = y_0 + \frac{2 \cdot q}{p + \sqrt{p^2 - 2 \cdot q \cdot [2 - G^2 \cdot (1/\Delta_0 + \Delta_{\text{ns}} \cdot \Delta_0)]}}
\end{aligned} \right. \tag{4.17}
\end{aligned}$$

4.3 Calculation of the Surface Potential in the Overlap Regions

A macro Φ_{ov} is defined to calculate the surface potential in the overlap regions with output x_{ov} and inputs: $x_g, G_{ov}, G_{ov}^2, x_{mrgov}, \xi_{ov}, x_{g1}$.

$$x_{ov}(x_g) = \begin{cases} \text{if } x_g < -x_{mrgov} \left\{ \begin{array}{l} y_g = -x_g \\ z = x_1 \cdot y_g / \xi_{ov} \\ \eta = \left[z + 10 - \sqrt{(z-6)^2 + 64} \right] / 2 \\ a = (y_g - \eta)^2 + G_{ov}^2 \cdot (\eta + 1) \\ c = 2 \cdot (y_g - \eta) - G_{ov}^2 \\ \tau = -\eta + \ln(a / G_{ov}^2) \\ y_0 = \sigma_1(a, c, \tau, \eta) \\ \Delta_0 = \exp(y_0) \\ p = 2 \cdot (y_g - y_0) + G_{ov}^2 \cdot (\Delta_0 - 1) \\ q = (y_g - y_0)^2 + G_{ov}^2 \cdot (y_0 - \Delta_0 + 1) \\ x_{ov} = -y_0 - \frac{2 \cdot q}{p + \sqrt{p^2 - 2 \cdot q \cdot (2 - G_{ov}^2 \cdot \Delta_0)}} \end{array} \right. \\ \text{if } |x_g| < x_{mrgov} \left\{ \begin{array}{l} x_{ov} = x_g / \xi_{ov} \end{array} \right. \\ \text{if } x_g > x_{mrgov} \left\{ \begin{array}{l} \bar{x} = x_g / \xi_{ov} \cdot \left[1 + x_g \cdot (\xi_{ov} \cdot x_1 - x_{g1}) / x_{g1}^2 \right] \\ \omega = \begin{cases} 1 - \exp(-\bar{x}), & \text{if } \bar{x} < k_{se2} \\ 1 - \frac{10^{-200}}{\text{P3}(\bar{x} - k_{se2})}, & \text{otherwise} \end{cases} \\ x_0 = x_g + G_{ov}^2 / 2 - G_{ov} \cdot \sqrt{x_g + G_{ov}^2 / 4 - \omega} \\ \Delta_0 = \begin{cases} \exp(-x_0), & \text{if } x_0 < k_{se2} \\ \frac{10^{-200}}{\text{P3}(x_0 - k_{se2})}, & \text{otherwise} \end{cases} \\ p = 2 \cdot (x_g - x_0) + G_{ov}^2 \cdot (1 - \Delta_0) \\ q = (x_g - x_0)^2 - G_{ov}^2 \cdot (x_0 + \Delta_0 - 1) \\ x_{ov} = x_0 + \frac{2 \cdot q}{p + \sqrt{p^2 - 2 \cdot q \cdot (2 - G_{ov}^2 \cdot \Delta_0)}} \end{array} \right. \end{cases} \quad (4.18)$$

4.4 Surface Potential without Poly Effect

$$V_{\text{gb1}} = \mathbf{TYPE} \cdot (V_C - V_{\text{fb}, \text{T}}) \quad (4.19)$$

$$x_g = V_{\text{gb1}} / \phi_{\text{T}} \quad (4.20)$$

The macro Φ_s (defined in Section 4.2) calculates the normalized surface potential (i.e., ϕ_s / ϕ_{T}).

$$x_{\text{s0}} = \Phi_s(x_g, x_{\text{ns}}, \Delta_{\text{ns}}, G_s, G_s^2, G_s^{-2}, \xi_s, \xi_s^{-1}, x_{\text{mrgrs}}) \quad (4.21)$$

$$\psi_{\text{s0}} = x_{\text{s0}} \cdot \phi_{\text{T}}. \quad (4.22)$$

4.5 Surface Potential with Poly Effect

Polysilicon space charge region is one area where varactor model differs significantly from PSP model. In varactor model polysilicon is allowed to enter inversion region. Furthermore, the effect of polysilicon finite doping is included for all gate biases (in PSP polysilicon effect is not included when device operates in accumulation).

Note also that even when the frequency dependent inversion layer formation is activated in the varactor model of the active region, the polysilicon surface potential is still computed using quasi-static approximation.

When $\mathbf{NPO} \geq 10^{27}$, $\psi_{\text{p0}} = 0$. The following calculates the poly surface potential when $\mathbf{NPO} < 10^{27}$.

$$x_{\text{gp}} = -\mathbf{TYPE} \cdot \mathbf{TYPEP} \cdot (V_{\text{gb1}} - \psi_{\text{s0}}) / \phi_{\text{T}} \quad (4.23)$$

$$x_{\text{p0}} = \Phi_s(x_{\text{gp}}, x_{\text{np}}, \Delta_{\text{np}}, G_p, G_p^2, G_p^{-2}, \xi_p, \xi_p^{-1}, x_{\text{mrgrp}}) \quad (4.24)$$

$$\psi_{\text{p0}} = -\mathbf{TYPE} \cdot \mathbf{TYPEP} \cdot x_{\text{p0}} \cdot \phi_{\text{T}} \quad (4.25)$$

$$x_g = (V_{\text{gb1}} - \psi_{\text{p0}}) / \phi_{\text{T}} \quad (4.26)$$

$$x_{\text{s0}} = \Phi_s(x_g, x_{\text{ns}}, \Delta_{\text{ns}}, G_s, G_s^2, G_s^{-2}, \xi_s, \xi_s^{-1}, x_{\text{mrgrs}}) \quad (4.27)$$

$$\psi_{\text{s0}} = x_{\text{s0}} \cdot \phi_{\text{T}}. \quad (4.28)$$

4.6 Static Inversion Charge Calculations

The following computes surface potential-related variables and inversion charge.

$$\text{If } x_g \leq 0 \quad q_{\text{is}} = 0 \quad (4.29)$$

When $x_g > 0$ (namely the depletion and inversion regions), the following is performed to find q_{is} and q_{eff} .

$$\Delta_{\text{ls}} = 0 \quad (4.30)$$

$$\left\{ \begin{array}{l} \text{If } x_{s0} < k_{se1} \\ \text{elseif } x_{s0} > x_{ns} - k_{se1} \\ \text{else} \end{array} \right. \left\{ \begin{array}{l} \Delta_{ls1} = \exp(x_{s0}) \\ E_s = \Delta_{ls1}^{-1} \\ \Delta_{ls} = \Delta_{ns} \cdot \Delta_{ls1} \\ D_s = \Delta_{ns} \cdot (E_s^{-1} - x_{s0} - 1) \\ \Delta_{ls} = \exp(x_{s0} - x_{ns}) \\ E_s = \Delta_{ns} / \Delta_{ls} \\ D_s = \Delta_{ls} - \Delta_{ns} \cdot (x_{s0} + 1) \\ \Delta_{ls} = \frac{10^{-100}}{\text{P3}(x_{ns} - x_{s0} - k_{se1})} \\ E_s = \frac{10^{-100}}{\text{P3}(x_{s0} - k_{se1})} \\ D_s = \Delta_{ls} - \Delta_{ns} \cdot (x_{s0} + 1) \end{array} \right. \quad (4.31)$$

$$\left\{ \begin{array}{l} \text{If } x_{s0} < 10^{-5} \\ \text{else} \end{array} \right. \left\{ \begin{array}{l} P_s = 0.5 \cdot x_{s0}^2 \cdot \left[1 - \frac{1}{3} x_{s0} \cdot (1 - 0.25 \cdot x_{s0}) \right] \\ D_s = \frac{1}{6} \Delta_{ns} \cdot x_{s0}^3 \cdot (1 + 1.75 \cdot x_{s0}) \\ S_{qs} = x_{s0} \cdot \sqrt{0.5 - \frac{1}{6} x_{s0} \cdot (1 - 0.25 \cdot x_{s0})} \\ P_s = x_{s0} + E_s - 1 \\ S_{qs} = \sqrt{P_s} \end{array} \right. \quad (4.32)$$

$$\begin{aligned} x_{gs} &= G_s \cdot \sqrt{P_s + D_s} \\ q_{is} &= \phi_{\mathbf{T}} \cdot G_s^2 \cdot D_s / (x_{gs} + G_s \cdot S_{qs}) \end{aligned} \quad (4.33)$$

The normalized static inversion charge is

$$Q_{i0} = -q_{is} \quad (4.34)$$

4.7 Time-Dependent Silicon Surface Potential Calculation without Poly Effect

$$x_{g,t} = (V_{gb1} + V_n) / \phi_{\mathbf{T}}, \quad (4.35)$$

where V_n is the voltage at the internal time-constant node \mathbf{n} .

$$x_s = \Phi_{ov}(x_{g,t}, G_s, G_s^2, x_{mrgs}, \xi_s, x_{g1}), \quad (4.36)$$

where Φ_{ov} calculates the normalized surface potential and is defined in Section 4.3.

$$\psi_s = x_s \cdot \phi_{\mathbf{T}} \quad (4.37)$$

4.8 Time-Dependent Poly Surface Potential Calculation Correction

If $NPO \geq 10^{27}$, $\psi_p = 0$. Otherwise, the following procedure is used.

$$x_{gp,t} = -\mathbf{TYPE} \cdot \mathbf{TYPEP} \cdot (V_{gb1} - \psi_s) / \phi_T \quad (4.38)$$

$$x_p = \Phi_s(x_{gp,t}, x_{np}, \Delta_{np}, G_p, G_p^2, G_p^{-2}, \xi_p, \xi_p^{-1}, x_{mrp}) \quad (4.39)$$

$$\psi_p = -\mathbf{TYPE} \cdot \mathbf{TYPEP} \cdot x_p \cdot \phi_T \quad (4.40)$$

$$x_{g,t} = (V_{gb1} + V_n - \psi_p) / \phi_T \quad (4.41)$$

$$x_s = \Phi_{ov}(x_{g,t}, G_s, G_s^2, x_{mrsg}, \xi_s, x_{g1}) \quad (4.42)$$

$$\psi_s = x_s \cdot \phi_T \quad (4.43)$$

4.9 Quantum Mechanical Corrections

$$\Delta_{ls} = 0 \quad (4.44)$$

$$\left\{ \begin{array}{l} \text{If } x_s < k_{se1} \\ \text{elseif } x_s > x_{ns} - k_{se1} \\ \text{else} \end{array} \right\} \left\{ \begin{array}{l} \Delta_{ls} = \exp(x_s) \\ E_s = \Delta_{ls}^{-1} \\ \Delta_{ls} = \exp(x_{ns} - x_s) \\ E_s = \Delta_{ns} \cdot \Delta_{ls} \\ E_s = \frac{10^{-100}}{P3(x_s - k_{se1})} \end{array} \right. \quad (4.45)$$

$$\left\{ \begin{array}{l} \text{If } x_s < -x_{mrsg} \\ \text{else if } abs(x_s) \leq x_{mrsg} \\ \text{else} \end{array} \right\} \left\{ \begin{array}{l} P_s = E_s + x_s - 1.0 \\ S_{qs} = -\sqrt{P_s} \\ P_s = 0.5 \cdot x_s^2 \cdot \left[1 - \frac{1}{3} x_s \cdot (1 - 0.25 \cdot x_s) \right] \\ S_{qs} = x_s \cdot \sqrt{0.5 - \frac{1}{6} x_s \cdot (1 - 0.25 \cdot x_s)} \\ P_s = x_s + E_s - 1 \\ S_{qs} = \sqrt{P_s} \end{array} \right. \quad (4.46)$$

$$\begin{aligned} q_{bs} &= \phi_T \cdot S_{qs} \cdot G_s \\ \epsilon &= 1.62 \cdot [(1 + norm_{nsub}) \cdot (1 + 0.37 \cdot norm_{tox})]^2 \cdot \left(\frac{T_{KR}}{T_{KD}} \right)^{1.5} \cdot \phi_T^2; \\ q_{eff} &= \text{MAXA}(q_{bs}, -q_{bs}, \epsilon) + \eta_\mu \cdot \text{MAXA}(-V(b_{cn}), V(b_{cn}), \epsilon) \end{aligned} \quad (4.47)$$

The following $C_{\text{ox}, \text{qm}}$ calculation is for all regions ($x_g \leq 0$ and $x_g > 0$).

$$C_{\text{ox}, \text{qm}} = \begin{cases} C_{\text{ox}}, & q_q = 0 \\ \frac{C_{\text{ox}}}{1 + q_q \cdot (q_{\text{eff}}^2 + q_{\text{lim}2})^{-1/6}}, & q_q > 0 \end{cases} \quad (4.48)$$

4.10 Accumulation Resistance Bias Dependence

$$f_{\text{rac}} = \begin{cases} \phi_{\text{T}} \cdot \exp(-10), & \text{if } x_{s0} > 10 \\ \phi_{\text{T}} \cdot \exp(-x_{s0}), & \text{otherwise} \end{cases} \quad (4.49)$$

$$q_{\text{ac}} = \gamma_s \cdot C_{\text{ox}, \text{qm}} \cdot \sqrt{f_{\text{rac}}} \quad (4.50)$$

$$m_{\text{axs}} = 0.5 \cdot \left(-V_{\text{gb}1} + \sqrt{V_{\text{gb}1}^2 + 0.04} \right) \quad (4.51)$$

$$G_{\text{ac}} = G_{\text{ac}0} \cdot q_{\text{ac}} / (1 + \text{UACRED} \cdot m_{\text{axs}}) \quad (4.52)$$

4.11 Calculation of Gate Tunneling Current

A macro I_{gate} is defined as a function of I_{gin} , I_{ginHVB} , E_g , V_{ov} , D_{ch} , $D_{\text{ch}, \text{HVB}}$, INV_{CHIB} , $\text{INV}_{\text{CHIB}, \text{HVB}}$, **GC2O**, **GC3O**, **GC2HVO**, **GC3HVO**, Q_{CQ} , $I_{\text{g}, \text{type}}$, x_s , $\alpha_{\text{b}, \text{s}}$, $\alpha_{\text{b}, \text{ov}}$, ϕ_{T}^{-1} , **TYPEP**, **TYPE**, $V_{\text{bcf}, \text{ig}}$, B_{OV} , and $B_{\text{OV}, \text{HVB}}$ as shown in the following with I_{gout} as output. It is used for the calculation of gate tunneling current. See Figure 4.1 for different gate tunneling mechanisms.

$$I_{\text{gout}} = 0 \quad (4.53)$$

$$\text{If } \text{TYPEP} = 1 \left\{ \begin{array}{l} \psi_t = \text{MAXA}(0, \text{TYPE} \cdot V_{\text{ov}} + D_{\text{ch}, \text{HVB}}, 0.01) \\ z_g = \sqrt{V_{\text{ov}}^2 + 10^{-6}} \cdot \text{INV}_{\text{CHIB}, \text{HVB}} \\ \text{If } \text{GC3HVO} < 0 \\ \quad z_g = \text{MINA}(z_g, Q_{\text{CQ}}, 10^{-6}) \\ \text{endif} \\ \Delta_{\text{si}} = \begin{cases} \exp[-\text{TYPE} \cdot x_s - (E_g - \alpha_{\text{b}, \text{ov}} + \psi_t) \cdot \phi_{\text{T}}^{-1}], & \text{if } I_{\text{g}, \text{type}} = 0 \\ \exp[-\text{TYPE} \cdot x_s - (E_g - \alpha_{\text{b}, \text{s}} + \psi_t) \cdot \phi_{\text{T}}^{-1}], & \text{if } I_{\text{g}, \text{type}} = 1 \end{cases} \\ \Delta_{\text{gate}} = \Delta_{\text{si}} \cdot \exp(\text{TYPE} \cdot V_{\text{bcf}, \text{ig}} \cdot \phi_{\text{T}}^{-1}) \\ D = \exp\{B_{\text{OV}} \cdot [-1.5 + z_g \cdot (\text{GC2HVO} + \text{GC3HVO} \cdot z_g)]\} \\ I_{\text{gout}, \text{HVB}} = I_{\text{ginHVB}} \cdot D \cdot \text{TYPE} \cdot \ln\left(\frac{1.0 + \Delta_{\text{gate}}}{1.0 + \Delta_{\text{si}}}\right) \end{array} \right. \quad (4.54)$$

$$\psi_t = \text{MINA}(0, \text{TYPE} \cdot V_{\text{ov}} + D_{\text{ch}}, 0.01) \quad (4.55)$$

$$z_g = \sqrt{V_{\text{ov}}^2 + 10^{-6}} \cdot \text{INV}_{\text{CHIB}} \quad (4.56)$$

If **GC30** < 0

$$z_g = \text{MINA}(z_g, Q_{\text{CQ}}, 10^{-6}) \quad (4.57)$$

endif

$$\Delta_{\text{si}} = \begin{cases} \exp(\mathbf{TYPE} \cdot x_s + (-\alpha_{\text{b,ov}} + \psi_t) \cdot \phi_{\mathbf{T}}^{-1}), & \text{if } I_{\text{g,type}} = 0 \\ \exp(\mathbf{TYPE} \cdot x_s + (-\alpha_{\text{b,s}} + \psi_t) \cdot \phi_{\mathbf{T}}^{-1}), & \text{if } I_{\text{g,type}} = 1 \end{cases} \quad (4.58)$$

$$\Delta_{\text{gate}} = \Delta_{\text{si}} \cdot \exp(-\mathbf{TYPE} \cdot V_{\text{bcf,ig}} \cdot \phi_{\mathbf{T}}^{-1}) \quad (4.59)$$

$$D = \exp\{B_{\text{OV}} \cdot [-1.5 + z_g \cdot (\mathbf{GC20} + \mathbf{GC30} \cdot z_g)]\} \quad (4.60)$$

$$I_{\text{gout,ECB}} = I_{\text{gin}} \cdot D \cdot \mathbf{TYPE} \cdot \ln\left(\frac{1.0 + \Delta_{\text{si}}}{1.0 + \Delta_{\text{gate}}}\right) \quad (4.61)$$

$$I_{\text{gout}} = I_{\text{gout,HVB}} + I_{\text{gout,ECB}} \quad (4.62)$$

4.12 Gate Tunneling Current

$$V_{\text{fb,ov}} = \begin{cases} \mathbf{TYPEP} \cdot E_g, & \text{if } \mathbf{TYPE} \cdot \mathbf{TYPEP} = -1 \\ 0, & \text{otherwise} \end{cases} \quad (4.63)$$

$$x_{g,\text{ov}} = \mathbf{TYPE} \cdot V_{C,\text{fr}} / \phi_{\mathbf{T}}, \quad (4.64)$$

where $V_{C,\text{fr}}$ is the voltage across the capacitance C_{fr} .

If $\mathbf{SWIGATE} \neq 0$ and $I_{\text{gov}} + I_{\text{govHVB}} > 0$

$$x_{\text{ov,s0}} = \Phi_{\text{ov}}(x_{g,\text{ov}}, G_{\text{ov,s}}, G_{\text{ov,s}}^2, x_{\text{mrgov,s}}, \xi_{\text{ov,s}}, x_{g1,\text{ov}}) \quad (4.65)$$

$$V_{\text{ov}} = \phi_{\mathbf{T}} \cdot (x_{g,\text{ov}} - x_{\text{ov,s0}}) \quad (4.66)$$

else

$$V_{\text{ov}} = 0.0 \quad (4.67)$$

$$x_{\text{ov,s0}} = 0.0 \quad (4.68)$$

end

$$I_{\text{GC}} = 0.0 \quad (4.69)$$

$$I_{\text{GOV}} = 0.0 \quad (4.70)$$

If $\mathbf{SWIGATE} = \text{true}$

$$V_{\text{bcf,ig}} = V_{C,\text{fr}} \cdot \mathbf{TYPE} \quad (4.71)$$

If $I_{\text{gov}} + I_{\text{govHVB}} > 0$

$$\begin{aligned} I_{\text{GOV}} = I_{\text{gate}}(I_{\text{gov}}, I_{\text{govHVB}}, E_g, V_{\text{ov}}, D_{\text{ch}}, D_{\text{ch,HVB}}, \text{INV}_{\text{CHIB}}, \text{INV}_{\text{CHIB,HVB}}, \mathbf{GC2O}, \\ \mathbf{GC3O}, \mathbf{GC2HVO}, \mathbf{GC3HVO}, Q_{\text{CQ}}, 0, x_{\text{ov,s0}}, \alpha_{\text{b,s}}, \alpha_{\text{b,ov}}, \phi_{\mathbf{T}}^{-1}, \mathbf{TYPEP}, \mathbf{TYPE}, \\ V_{\text{bcf,ig}}, B_{\text{OV}}, B_{\text{OV,HVB}}) \text{end} \end{aligned} \quad (4.72)$$

If $I_{\text{ginv}} + I_{\text{gcHVB}} > 0$

$$\begin{aligned} V_{\text{ox}} = (x_g - x_s) \cdot \phi_{\mathbf{T}} \\ I_{\text{GC}} = I_{\text{gate}}(I_{\text{ginv}}, I_{\text{gcHVB}}, E_g, V_{\text{ox}}, D_{\text{ch}}, D_{\text{ch,HVB}}, \text{INV}_{\text{CHIB}}, \text{INV}_{\text{CHIB,HVB}}, \mathbf{GC2O}, \\ \mathbf{GC3O}, \mathbf{GC2HVO}, \mathbf{GC3HVO}, Q_{\text{CQ}}, 1, x_s, \alpha_{\text{b,s}}, \alpha_{\text{b,ov}}, \phi_{\mathbf{T}}^{-1}, \mathbf{TYPEP}, \mathbf{TYPE}, \\ V_{\text{bcf,ig}}, B_{\text{CH}}, B_{\text{CH,HVB}}) \text{end} \end{aligned} \quad (4.73)$$

end

Note that macro I_{gate} is defined in Section 4.11.

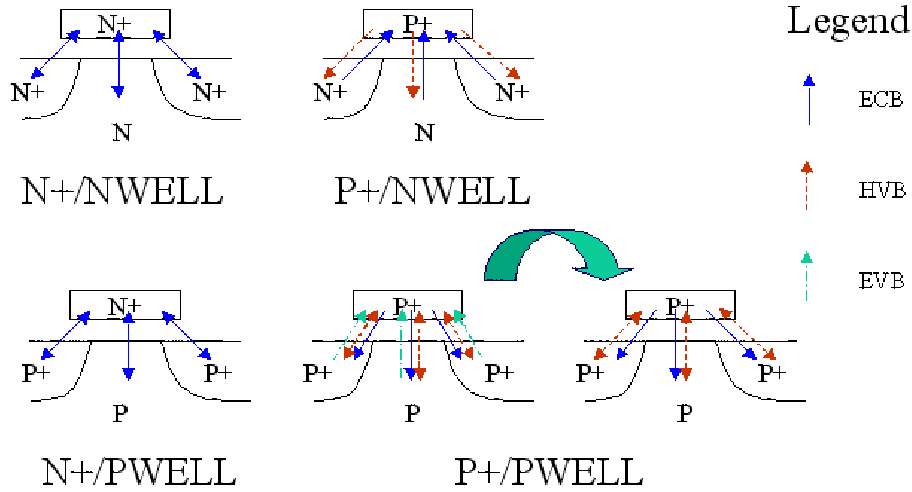


Figure 4.1: Different gate tunneling mechanisms.

4.13 Terminal Currents

4.13.1 DC Currents

$$\text{Current through the gate } I_{g, DC} = m \cdot (I_{GC} + I_{GOV}), \quad (4.75)$$

$$\text{Current through the bulk } I_{b, DC} = -m \cdot (I_{GC} + I_{GOV}) \quad (4.76)$$

4.13.2 AC Currents

$$\text{Current through the gate } I_{g, AC} = m \cdot \left(\frac{dQ_g}{dt} + \frac{dQ_{fr}}{dt} \right) \quad (4.77)$$

$$\text{Current through the bulk } I_{b, AC} = -m \cdot \left(\frac{dQ_g}{dt} + \frac{dQ_{fr}}{dt} \right) \quad (4.78)$$

4.14 Terminal Charges

Total charges at the gate

$$Q_{g, total} = (V_{gb1} - \phi_s - \phi_p) \cdot L_{eff} \cdot W_{eff} \cdot C_{ox, qm} \cdot \mathbf{TYPE} + C_{fr} \cdot V_{C, fr} \quad (4.79)$$

Total charges at the bulk

$$Q_{b, total} = -(V_{gb1} - \phi_s - \phi_p) \cdot L_{eff} \cdot W_{eff} \cdot C_{ox, qm} \cdot \mathbf{TYPE} - C_{fr} \cdot V_{C, fr} \quad (4.80)$$

4.15 Noise

Thermal noise contributions from *rgsal*, *rgpv*, *rend*, *rsub* and *rac0* are calculated when **SWRES** = 1.

In short circuit case, noise contribution is 0. This is realized in the code by setting $ggsal$, $ggpv$, $gend$, $gsub$ and $gac0$ to 0.

Listed below are major equations for noise calculation.

$$rgsalnoise = m \cdot nt0 \cdot ggsal \quad (4.81)$$

$$rgpvnoise = m \cdot nt0 \cdot ggpv \quad (4.82)$$

$$rendnoise = m \cdot nt0 \cdot gend \quad (4.83)$$

$$rsubnoise = m \cdot nt0 \cdot gsub \quad (4.84)$$

$$rac0lnoise = m \cdot nt0 \cdot gac0 \quad (4.85)$$

Appendix A

Auxiliary Equations

In this Appendix, some auxiliary functions which are used in the model equations are defined.

The MINA-smoothing function:

$$\text{MINA}(x, y, a) = \frac{1}{2} \cdot \left[x + y - \sqrt{(x - y)^2 + a} \right] \quad (\text{A.1})$$

The MAXA-smoothing function:

$$\text{MAXA}(x, y, a) = \frac{1}{2} \cdot \left[x + y + \sqrt{(x - y)^2 + a} \right] \quad (\text{A.2})$$

σ_1 , and σ_2 , which are used in the explicit approximation of surface potential:

$$\nu = a + c \quad (\text{A.3})$$

$$\mu_1 = \frac{\nu^2}{\tau} + \frac{c^2}{2} - a \quad (\text{A.4})$$

$$\sigma_1(a, c, \tau, \eta) = \frac{a \cdot \nu}{\mu_1 + (c^2/3 - a) \cdot c \cdot \nu / \mu_1} + \eta \quad (\text{A.5})$$

$$\mu_2 = \frac{\nu^2}{\tau} + \frac{c^2}{2} - a \cdot b \quad (\text{A.6})$$

$$\sigma_2(a, b, c, \tau, \eta) = \frac{a \cdot \nu}{\mu_2 + (c^2/3 - a \cdot b) \cdot c \cdot \nu / \mu_2} + \eta \quad (\text{A.7})$$

A polynomial function:

$$\text{P3}(u) = 1 + u \cdot [1 + 0.5 \cdot u \cdot (1 + u/3)] \quad (\text{A.8})$$

Three functions are defined to prevent over-/under-flow for exponential functions:

$$\text{expl}(x) = \begin{cases} \exp(x), & \text{if } |x| < k_{\text{se1}} \\ \frac{10^{-100}}{\text{P3}(-k_{\text{se1}} - x)}, & \text{if } x < -k_{\text{se1}} \\ 10^{100} \cdot \text{P3}(x - k_{\text{se1}}), & \text{otherwise} \end{cases} \quad (\text{A.9})$$

$$\text{expl}_{\text{low}}(x) = \begin{cases} \exp(x), & \text{if } x > -k_{\text{se1}} \\ \frac{10^{-100}}{\text{P3}(-k_{\text{se1}} - x)}, & \text{otherwise} \end{cases} \quad (\text{A.10})$$

$$\text{expl}_{\text{high}}(x) = \begin{cases} \exp(x), & \text{if } x < k_{\text{se1}} \\ 10^{100} \cdot \text{P3}(x - k_{\text{se1}}), & \text{otherwise} \end{cases} \quad (\text{A.11})$$

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